

台積電2025年產學合作計畫 徵求提案

- 目的** 為邀請更多優秀學者參與半導體相關領域研究，台積公司擬公開徵求產學合作提案
- 對象** 國內各大學教授
- 方式** 若您對徵求提案之題目有興趣，歡迎填寫以下連結表單，我們會再寄送詳細資訊給您。
表單填寫截止日：即日起至2024年9月2日(含)止
若您看過詳細資訊後決定提案，請下載附件(simple)Proposal form填寫，並依照台積信件中的說明進行初步提案。
- 表單連結** <https://zh.surveymonkey.com/r/CTT9LB5>
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免責聲明:

- 產學合作主題及其詳細資訊屬於台積公司智慧財產，僅供有興趣之教授申請台積電2025年產學合作計畫之個人使用，不得移作其他用途。
- 教授申請之產學合作計畫提案不可包含機密資訊；申請教授同意產學合作計畫提案不包含機密資訊，僅供台積公司內部產學合作計畫審核使用。

台積電2025年產學合作計畫 題目

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| 1 AI-Driven Adaptive Power Planning from Floorplan to ECO | 8 Thin film interface characterization numerical and experimental methodology | 15 Machine-Learning-Assisted CFET MOL Layout Pattern Generation for Interconnect Resistance/Capacitance Modeling |
| 2 Compute-in-Memory Compilation Toolchain in a Multi-Core Architecture | 9 Advanced wafer-level thermal solution for SoIC technology | 16 Compact Modeling for Layout-Dependent Thermal Behavior of Circuits |
| 3 Advancing In-Memory P-bits with SOT/STT Magnetic Tunnel Junction Technology | 10 Through controlling phase shift and inverse design to achieve mode-controllable miniaturized mode division multiplexing devices | 17 Evaluation of Neural-Network-Based and Equation-Based Approaches for Predictive IV/CV Models of 2-D Devices |
| 4 Analysis of Contact Engineering of P-type SnO Transistors for BEOL Application | 11 Emerging CMP Technology for Advanced Interconnects | 18 Epitaxial nanosheet-structure to boost device in GAAFET technology |
| 5 Advanced magnetic materials for millimeter-Wave inductor | 12 Novel Materials with Anisotropic Conduction for Low-R Interconnect | 19 Study of new optical methods to provide distinct signals for different dielectric materials by using non-linear optical effects |
| 6 Conductive PO basefilm formulation and film property verification | 13 Dirac source MOSFET with steep subthreshold slope | 20 To simulate small trench and nano-sheet, WET chemical clean and lateral etch behavior (MG loop, H2O2/NH4OH, TIN ALO) |
| 7 Establish a Simulator and AI Model to Predict Thermosetting Material Flowability | 14 Smallest Thermal Strain Geometry Structure of CNT Networks | 21 二氧化碳再利用關鍵催化劑材料和轉換機制研究 |